



Material Content Data Sheet



Halogen-Free

Sales Product Name	BTS50010-1TAE	Issued	15. May 2021
MA#	MA004091370		
Package	PG-TO263-7-10	Weight*	1562.28 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip_1	inorganic material	silicon	7440-21-3	12.330	0.79	0.79	7893	7893
chip_2	inorganic material	silicon	7440-21-3	1.848	0.12	0.12	1183	1183
leadframe	inorganic material	phosphorus	7723-14-0	0.247	0.02		158	
	non noble metal	iron	7439-89-6	0.823	0.05		527	
	non noble metal	copper	7440-50-8	822.375	52.65	52.72	526396	527081
wire	non noble metal	aluminium	7429-90-5	19.444	1.24	1.24	12446	12446
encapsulation	inorganic material	zinc oxide	1314-13-2	5.513	0.35		3529	
	miscellaneous	miscellaneous	-	22.052	1.41		14115	
	plastics	epoxy resin	-	82.695	5.29		52933	
	inorganic material	silicon dioxide	60676-86-0	441.043	28.23	35.28	282308	352885
lead finish	non noble metal	tin	7440-31-5	12.163	0.78	0.78	7785	7785
plating	inorganic material	phosphorus	7723-14-0	0.007			5	
	non noble metal	nickel	7440-02-0	2.941	0.19	0.19	1882	1887
solder	non noble metal	tin	7440-31-5	0.157	0.01		100	
	noble metal	silver	7440-22-4	0.196	0.01		125	
	non noble metal	lead	7439-92-1	7.483	0.48	0.50	4790	5015
glue	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	127	127
heatspreader	inorganic material	phosphorus	7723-14-0	0.039			25	
	non noble metal	iron	7439-89-6	0.131	0.01		84	
	non noble metal	copper	7440-50-8	130.589	8.36	8.37	83589	83698
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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